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	Type	L #	Hits	Search Text	DBs	Time Stamp
1	BRS	L1	121397 6	"integrated circuit" or semiconductor	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/26 13:52
2	BRS	L2	45405	1 and adhesive	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/26 13:53
3	BRS	L3	7912	2 and laminate\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/26 13:54
4	BRS	L4	5936	3 and film	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/26 13:55
5	BRS	L5	2541	4 and cut\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/26 13:55
6	BRS	L6	2430	5 and @ad<19990730	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/26 13:55
7	BRS	L7	10113	"flip chip"	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/26 13:56
8	BRS	L8	940	6 and package	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/26 13:56
9	BRS	L9	46	8 and interposer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/26 14:08
10	BRS	L10	34647	adhesive near6 laminate\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/26 14:09
11	BRS	L11	1851	10 and 1	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/26 14:09
12	BRS	L12	1787	11 and @ad<19990730	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/26 14:10

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Type	L #	Hits	Search Text	DBs	Time Stamp
13 BRS	L13	652	12 and cut\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/26 14:23
14 BRS	L14	8	13 and interposer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/26 14:15
15 BRS	L15	894731	interposer or carrier	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/26 14:15
16 BRS	L16	235	13 and 15	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/26 14:15
17 BRS	L17	8	13 and interposer	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/26 14:16
18 BRS	L18	652	12 and cut\$	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/26 14:24
19 BRS	L19	251	18 and package	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/26 14:27
20 BRS	L20	104	19 and piece	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2001/07/26 14:28